



SEMITOP® 1

Antiparallel Thyristor Module

SK 70 KQ

Preliminary Data

Features

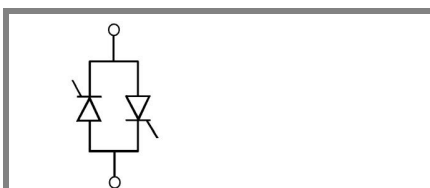
- Compact Design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DBC)
- Glass passivated thyristor chips
- Up to 1600V reverse voltage
- UL recognized, file no. E 63 532

Typical Applications*

- Soft starters
- Light control (studios, theaters...)
- Temperature control

V_{RSM} V	V_{RRM}, V_{DRM} V	$I_{RMS} = 72 \text{ A A (full conduction)}$ ($T_s = 85^\circ \text{C}$)
900	800	SK 70 KQ 08
1300	1200	SK 70 KQ 12
1700	1600	SK 70 KQ 16

Symbol	Conditions	Values	Units
I_{RMS}	W1C ; sin. 180° ; $T_s = 100^\circ \text{C}$ W1C ; sin. 180° ; $T_s = 85^\circ \text{C}$	50 72	A A
I_{TSM}	$T_{vj} = 25^\circ \text{C}$; 10 ms $T_{vj} = 125^\circ \text{C}$; 10 ms	1000 900	A A
i^2t	$T_{vj} = 25^\circ \text{C}$; 8,3...10 ms $T_{vj} = 125^\circ \text{C}$; 8,3...10 ms	5000 4000	A ² s A ² s
V_T $V_{T(TO)}$ r_T	$T_{vj} = 25^\circ \text{C}$, $I_T = 120 \text{ A}$ $T_{vj} = 125^\circ \text{C}$ $T_{vj} = 125^\circ \text{C}$	max. 1,8 max. 1 max. 6	V V mΩ
I_{DD}, I_{RD}	$T_{vj} = 25^\circ \text{C}$, $V_{RD} = V_{RRM}$ $T_{vj} = 125^\circ \text{C}$, $V_{RD} = V_{RRM}$	max. 0,5 max. 15	mA mA
t_{gd} t_{gr}	$T_{vj} = 25^\circ \text{C}$, $I_G = 1 \text{ A}$; $di_G/dt = 1 \text{ A}/\mu\text{s}$ $V_D = 0,67 \cdot V_{DRM}$	1 2	μs μs
$(dv/dt)_{cr}$ $(di/dt)_{cr}$	$T_{vj} = 125^\circ \text{C}$ $T_{vj} = 125^\circ \text{C}$; $f = 50...60 \text{ Hz}$	1000 50	V/μs A/μs
t_q I_H I_L	$T_{vj} = 125^\circ \text{C}$; typ. $T_{vj} = 25^\circ \text{C}$; typ. / max. $T_{vj} = 25^\circ \text{C}$; $R_G = 33 \Omega$; typ. / max.	80 100 / 200 200 / 400	μs mA mA
V_{GT} I_{GT} V_{GD} I_{GD}	$T_{vj} = 25^\circ \text{C}$; d.c. $T_{vj} = 25^\circ \text{C}$; d.c. $T_{vj} = 125^\circ \text{C}$; d.c. $T_{vj} = 125^\circ \text{C}$; d.c.	min. 2 min. 100 max. 0,25 max. 5	V mA V mA
$R_{th(j-s)}$ $R_{th(j-s)}$ T_{vj} T_{stg} T_{solder}	cont. per thyristor sin 180° per thyristor cont. per W1C sin 180° per W1C terminals, 10s	0,8 0,84 0,4 0,42 -40 ... +125 -40 ... +125 260	K/W K/W K/W K/W °C °C °C
V_{isol} M_s M_t a m	a. c. 50 Hz; r.m.s.; 1 s / 1 min. Mounting torque to heatsink	3000 / 2500 1,5 13	V~ Nm Nm m/s ² g
Case	SEMITOP® 1	T 1	



KQ

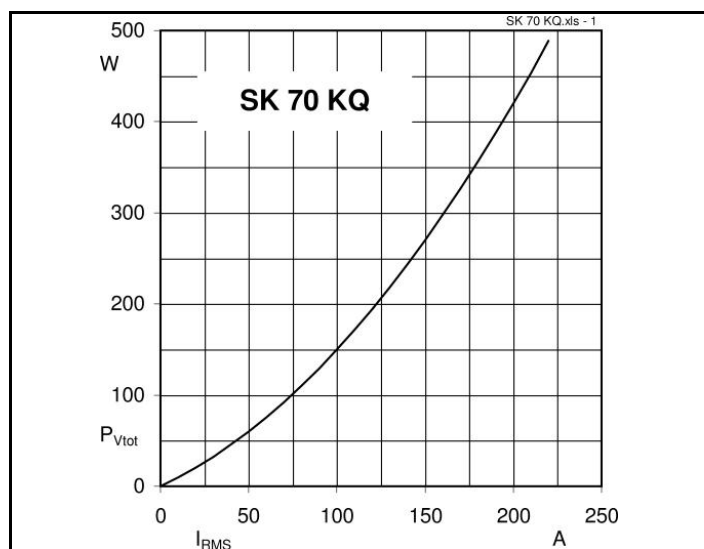


Fig. 1 Power dissipation per module vs. r.m.s. current

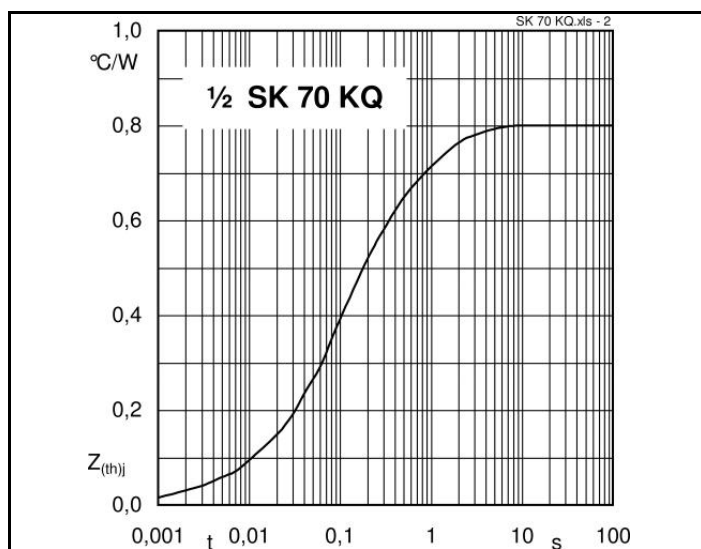


Fig. 2 Transient thermal impedance vs. time

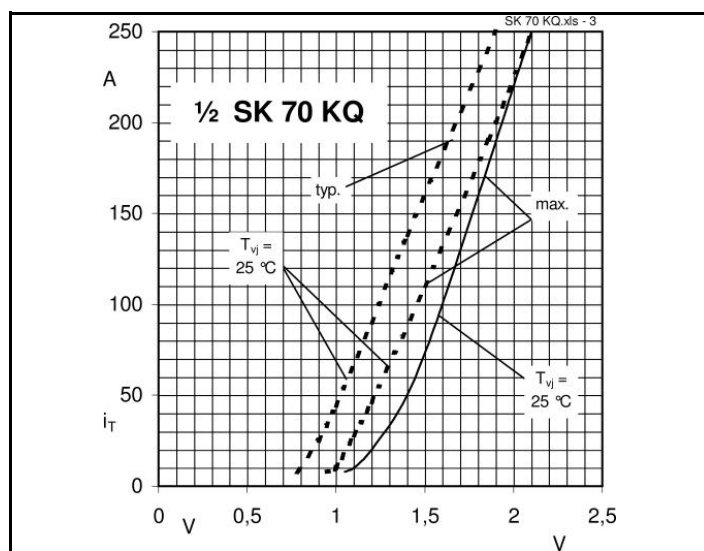


Fig. 3 On-state characteristics

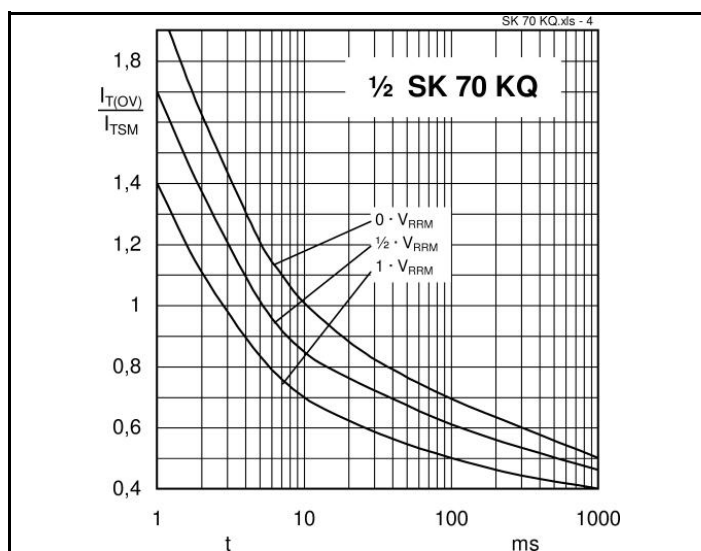


Fig. 4 Surge overload current vs. time

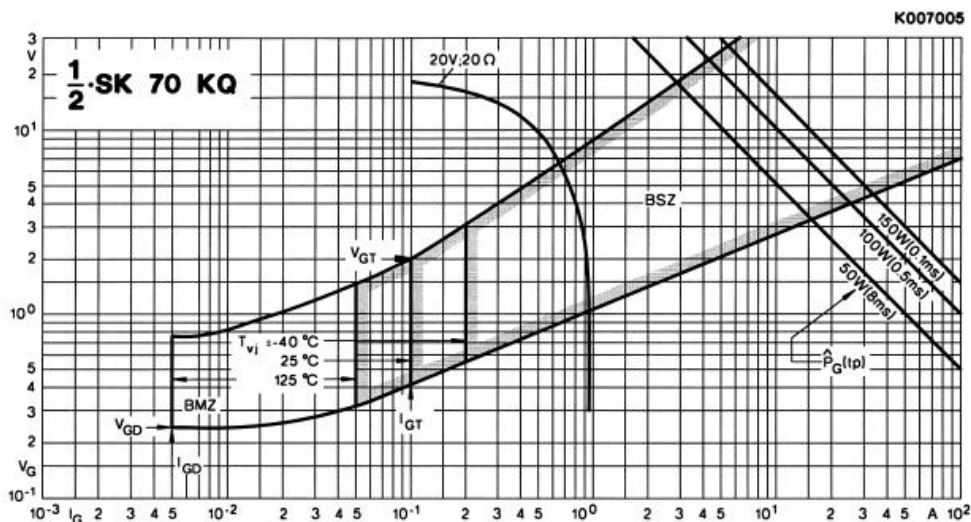
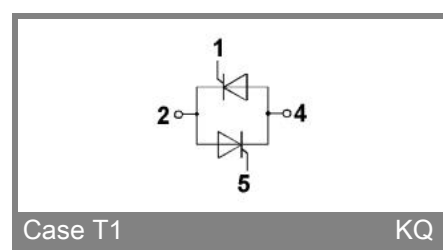
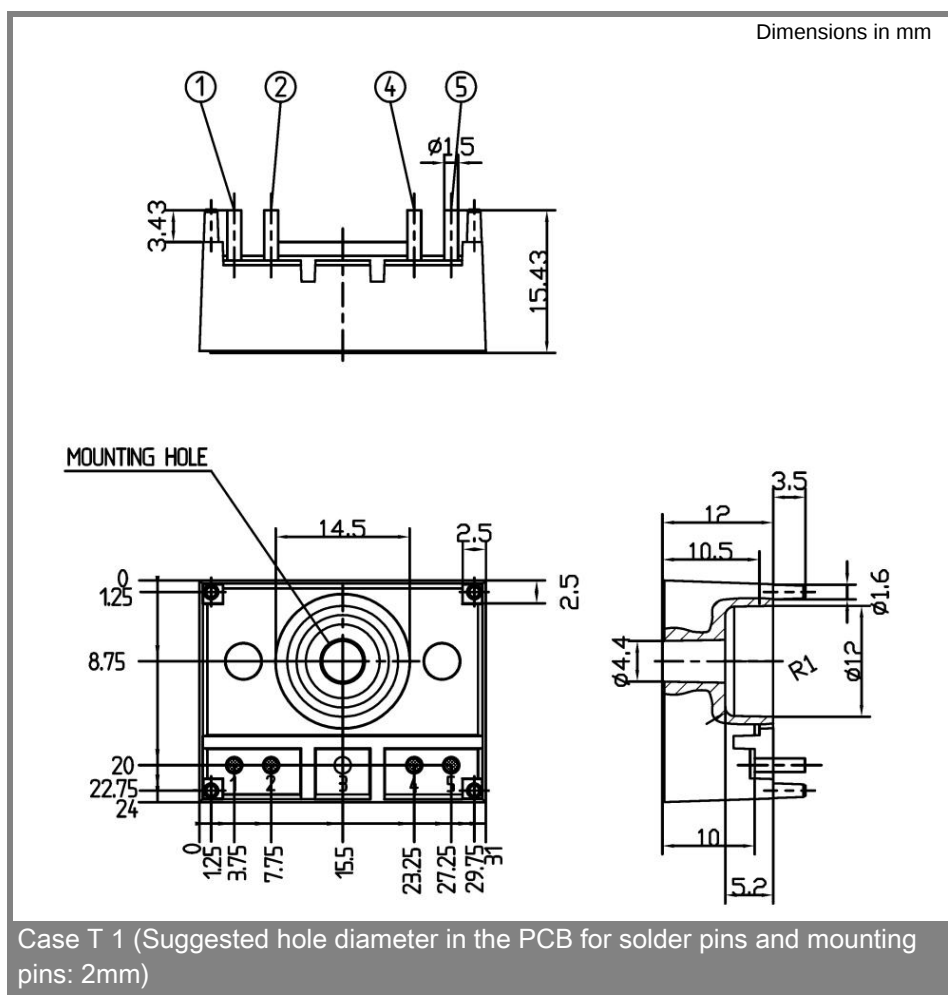


Fig. 5 Gate trigger characteristics



* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.